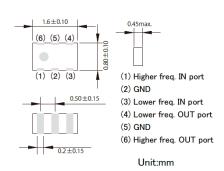
Spec Sheet

Multilayer Ceramic Devices (Dual Type)

FI168D087018-T



Features

- Item Summary
 Dual Type, 1.6x0.8x0.45mm
 for W-CDMA/CDMA/GSM/LTE
- Lifecycle Stage

Mass Production

- Standard packaging quantity (minimum)

Taping Papered 4000

Products characteristics table

System	W-CDMA/CDMA/GSM/LTE
Frequency1	Low band
Passband Frequency1 (f1)	824 to 915 MHz
Insertion Loss2 (max)(in f1)	0.6 dB at 824 to 915MHz (-30 to +85 ℃)
VSWR1 (max)(in f1)	1.5 at 824 to 915MHz
Attenuation1 (min)(f1)	25 dB at 1648 to 1830MHz
Attenuation2 (min)(f1)	25 dB at 2472 to 2745MHz
Frequency2	High band
Passband Frequency2 (f2)	1710 to 1910 MHz
Insertion Loss2 (max)(in f2)	0.6 dB at 1710 to 1910MHz (-30 to +85 ℃)
VSWR1 (max)(in f2)	1.5 at 1710 to 1910MHz
Attenuation1 (min)(f2)	25 dB at 3420 to 3820MHz
Attenuation2 (min)(f2)	25 dB at 5130 to 5730MHz
Isolation1 (min)	27 dB at 824 to 915MHz (In to In/Out to Out
Isolation2 (min)	30 dB at 1710 to 1910MHz (In to In/Out to O ut)
Isolation3 (min)	30 dB at 824 to 915MHz (In to Out)
Isolation4 (min)	30 dB at 1710 to 1910MHz (In to Out)
Input Impedance	50 Ω
Output Impedance	50 Ω
Operating Temp. Range	-30 to +85 ℃
RoHS2 Compliance (10 subst.)	Yes
REACH Compliance (173 subst.)	Yes
Halogen Free	Yes
Soldering	Reflow

■ External Dimensions

Dimension L	1.6 ±0.10 mm
Dimension W	0.8 ±0.10 mm
Dimension T	Max 0.45 mm

The data is reference only. Electrical characteristics vary depending on environment or measurement condition.

TAIYO YUDEN reserves the right to make change to the Date at any time without notice.

Before making final selection, please check product specification.

2017.04.30